

IN THE CLAIMS:

The status of each claim that has been introduced in the above-referenced application is identified in the ensuing listing of the claims. This listing of the claims replaces all previously submitted claims listings.

1. (Currently amended) A method for establishing an electrical contact with at least one semiconductor device, comprising:  
establishing an electrical contact between a first member of an electrical connector and a contact that is in electrical communication with the at least one semiconductor device; and magnetically drawing at least one of saidthe first member and saidthe contact toward the other of saidthe first member and saidthe contact.

2. (Currently amended) The method of claim 1, wherein said magnetically drawing is effected in a direction substantially normal to a plane of saidthe contact.

3. (Currently amended) The method of claim 1, wherein said magnetically drawing is effected in a direction substantially normal to a plane of a substrate upon which saidthe contact is carried.

4. (Currently amended) The method of claim 1, wherein said magnetically drawing is effected by positioning a second member of saidthe electrical connector opposite saidthe first member.

5. (Currently amended) The method of claim 4, wherein said magnetically drawing is effected by magnetically attracting at least one of saidthe first member and saidthe second member toward at least the other of saidthe first member and saidthe second member.

6. (Currently amended) The method of claim 4, wherein said magnetically drawing comprises securing saidthe first and second members to a substrate upon which saidthe contact is carried.

7. (Currently amended) The method of claim 1, wherein said magnetically drawing comprises magnetically securing saidthe first member to saidthe contact.

8. (Currently amended) A method for stress testing a plurality of semiconductor devices carried upon a common substrate and in communication with common ground and power contacts, comprising:  
establishing electrical contact between a first member of an electrical connector and at least one contact of the ground contact and the power contact; and  
magnetically drawing at least one of saidthe first member and saidthe at least one contact toward the other of saidthe first member and saidthe at least one contact.

9. (Currently amended) The method of claim 8, wherein said magnetically drawing is effected in a direction substantially normal to a plane of the common substrate.

10. (Withdrawn)

11. (Currently amended) The method of claim 8, wherein said magnetically drawing comprises positioning a second member of saidthe electrical connector opposite the substrate from saidthe first member.

12. (Currently amended) The method of claim 11, wherein at least one of saidthe first member and saidthe second member is drawn toward at least the other of saidthe first member and saidthe second member.

13. (Currently amended) The method of claim 12, wherein said magnetically drawing comprises magnetically attracting at least one of saidthe first member and saidthe second member toward at least the other of saidthe first member and saidthe second member.

14. (Currently amended) The method of claim 8, wherein said magnetically drawing comprises magnetically securing saidthe first member to saidthe at least one contact.

15. (Currently amended) The method of claim 8, wherein said magnetically drawing comprises securing at least saidthe first member in position relative to the substrate.

16. (Currently amended) The method of claim 8, further comprising:  
electrically connecting another first member of another electrical connector to another of the  
ground contact and the power contact; and  
magnetically drawing saidthe another first member toward saidthe another contact.

17. (Currently amended) The method of claim 16, further comprising:  
applying a substantially constant amount of current to each semiconductor device of the plurality  
of semiconductor devices through saidthe first member and saidthe another first member.

18. (Original) The method of claim 17, further comprising:  
heating each of the plurality of semiconductor devices.

19. (Currently amended) The method of claim 18, wherein said heating comprises  
cycling a temperature of each of the plurality of semiconductor devices.

20. (Currently amended) The method of claim 18, wherein said heating comprises  
varying a temperature of each of the plurality of semiconductor devices.